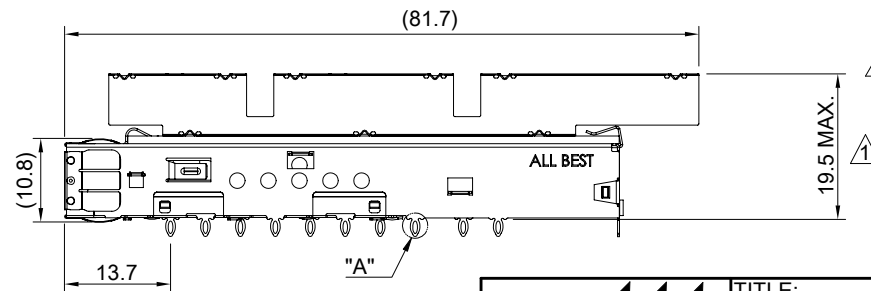
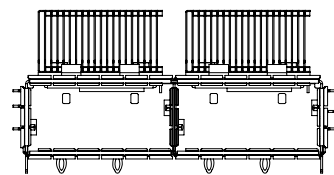


MATERIAL
 CAGE: NICKEL SILVER
 EMI SPRING: STAINLESS STEEL
 HEAT SINK: COPPER ALLOY
 HEAT SINK CLIP: STAINLESS STEEL

FINISH
 HEAT SINK: NICKEL OVER COPPER

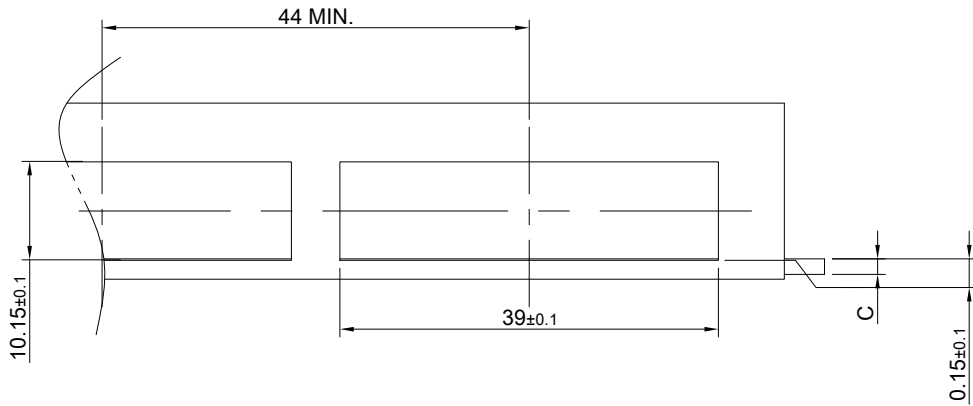
NOTE
 ▲ DIMENSION APPLIES WITH MODULE INSERTED IN CAGE



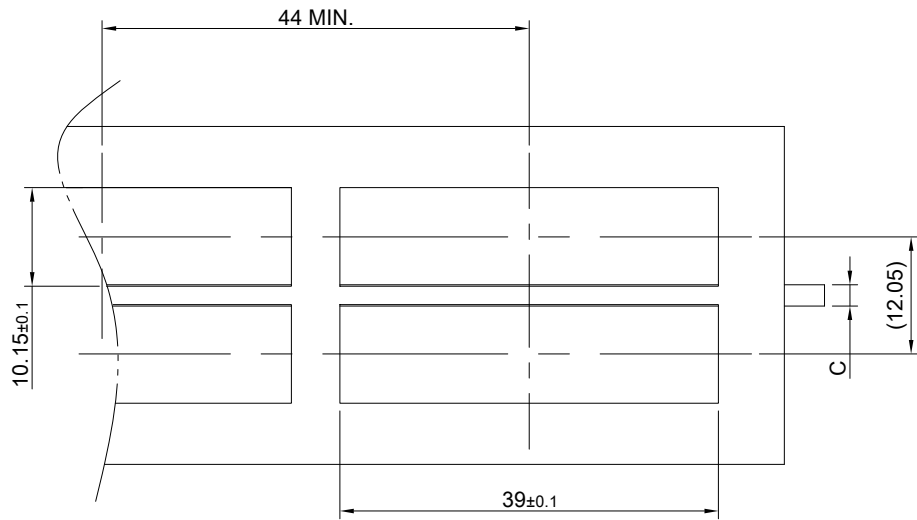
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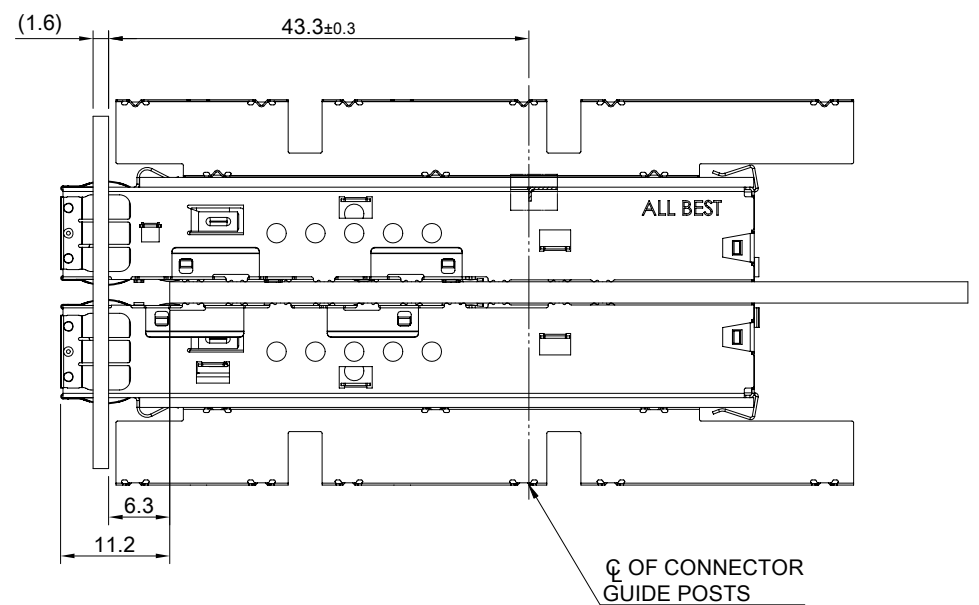
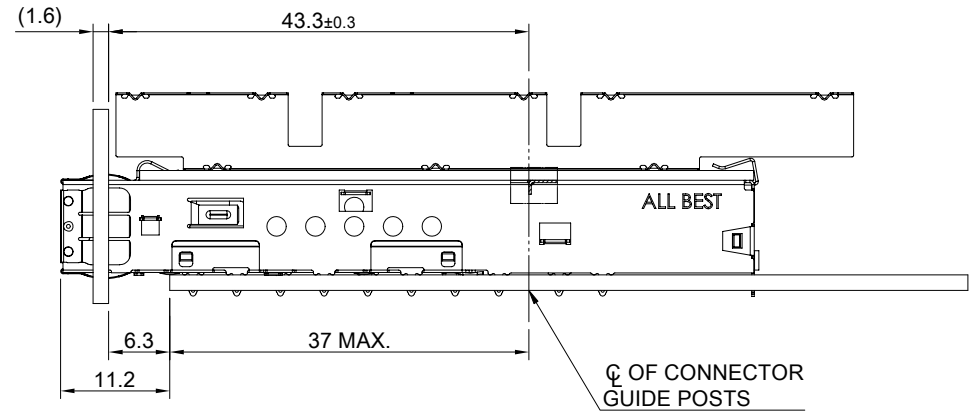
TITLE: QSFP-DD 1X2 Cage Assembly w/ Heat Sink			
DWG#: H-OR-DQD2-4CMFA3-TK		SHEET: 1/4	REV. REF.
UNIT: mm	SCALE: A4 1:1	CHECKED:	
TOLERANCE: Angle: ± 1° X ± 0.25 .X ± 0.20 .XX ± 0.15		MATERIAL: RoHS, HF Compliant	APPROVED:
THIRD ANGLE PROJECTION		DRAWN: Jason Zhao	DATE: 03/22/2024



SINGLE-SIDE CONFIGURATION



BELLY TO BELLY CONFIGURATION

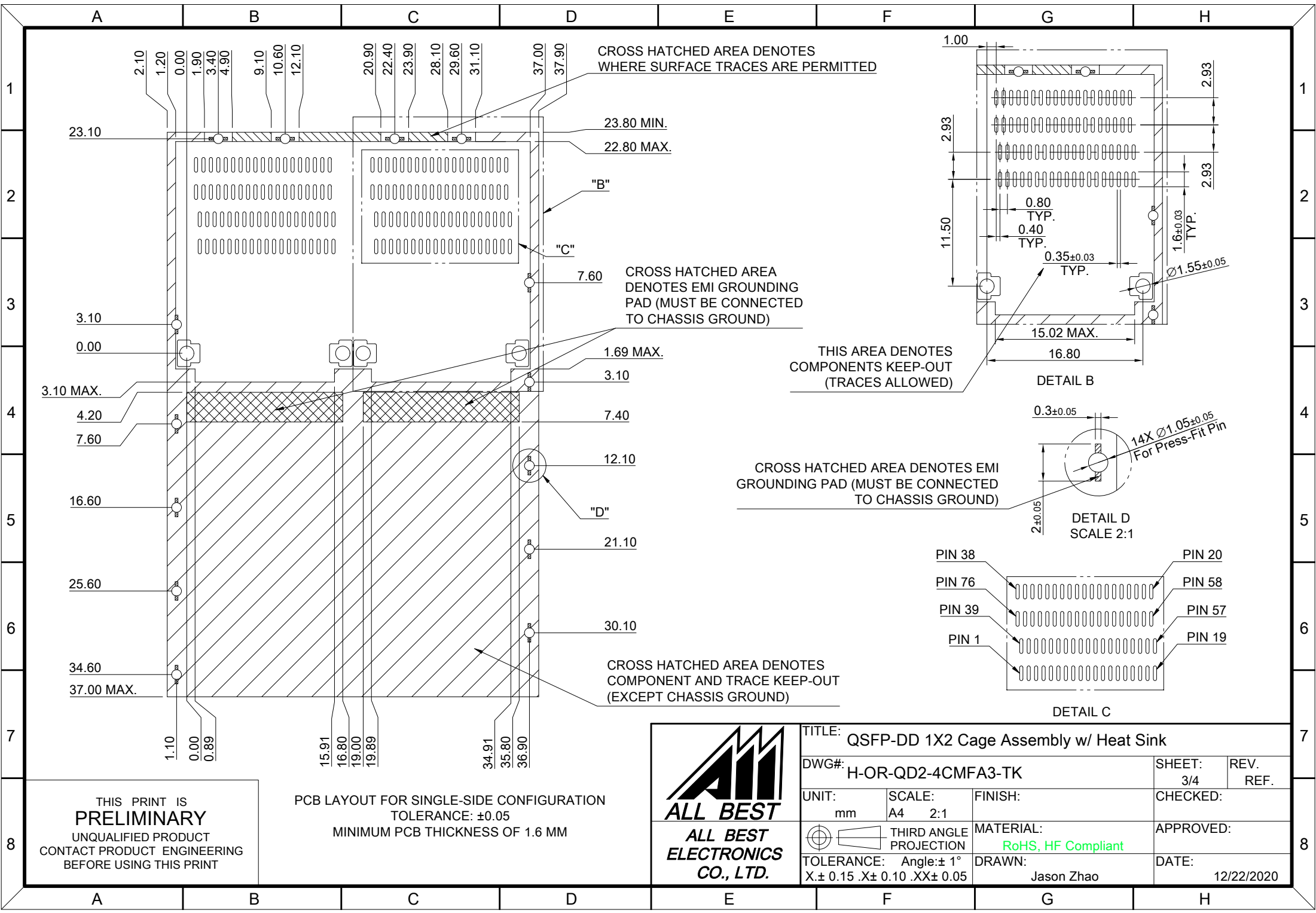


C = THICKNESS OF PC BOARD
 SINGLE-SIDE = 1.6MM (MIN.)
 BELLY TO BELLY = 2.2MM (MIN.)

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TITLE: QSFP-DD 1X2 Cage Assembly w/ Heat Sink			
DWG#: H-OR-QD2-4CMFA3-TK		SHEET: 2/4	REV. REF.
UNIT: mm	SCALE: A4 5:4	FINISH:	CHECKED:
TOLERANCE: Angle: ± 1° X ± 0.15 .X ± 0.10 .XX ± 0.05		MATERIAL: RoHS, HF Compliant	APPROVED:
THIRD ANGLE PROJECTION		DRAWN: Jason Zhao	DATE: 03/22/2024

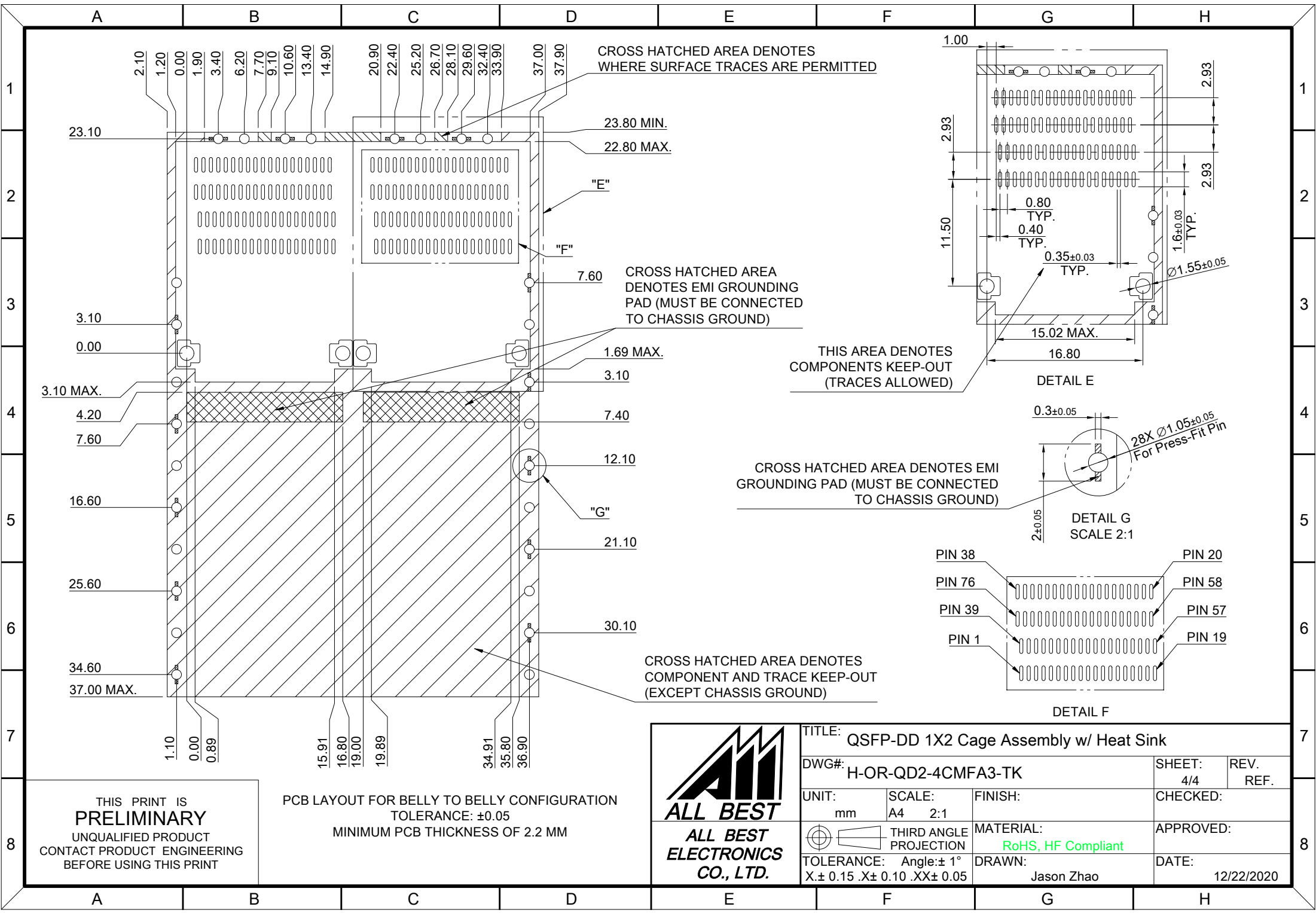


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PCB LAYOUT FOR SINGLE-SIDE CONFIGURATION
TOLERANCE: ±0.05
MINIMUM PCB THICKNESS OF 1.6 MM



TITLE: QSFP-DD 1X2 Cage Assembly w/ Heat Sink			
DWG#: H-OR-QD2-4CMFA3-TK		SHEET: 3/4	REV. REF.
UNIT: mm	SCALE: A4 2:1	CHECKED:	
THIRD ANGLE PROJECTION		APPROVED:	
TOLERANCE: Angle: ±1° X ± 0.15 .X ± 0.10 .XX ± 0.05		MATERIAL: RoHS, HF Compliant	DATE: 12/22/2020
		DRAWN: Jason Zhao	



CROSS HATCHED AREA DENOTES WHERE SURFACE TRACES ARE PERMITTED

23.80 MIN.
22.80 MAX.

"E"

"F"

7.60
CROSS HATCHED AREA DENOTES EMI GROUNDING PAD (MUST BE CONNECTED TO CHASSIS GROUND)

1.69 MAX.

3.10

7.40

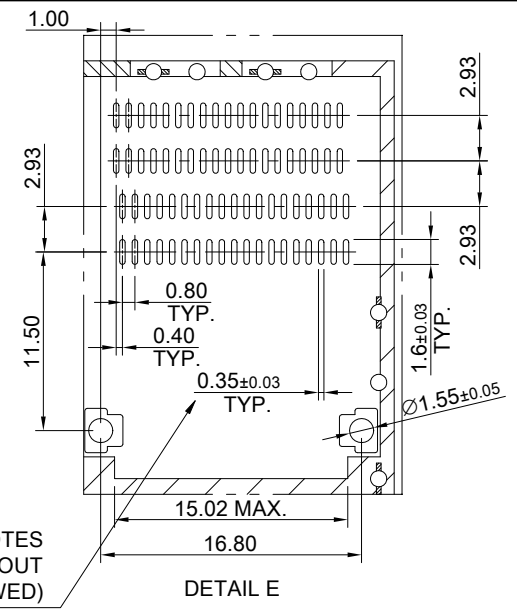
12.10

"G"

21.10

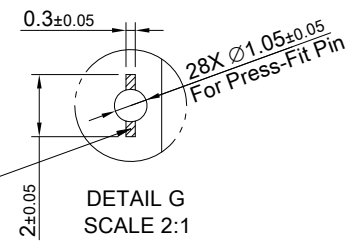
30.10

CROSS HATCHED AREA DENOTES COMPONENT AND TRACE KEEP-OUT (EXCEPT CHASSIS GROUND)

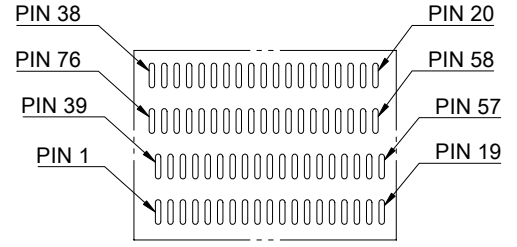


DETAIL E

CROSS HATCHED AREA DENOTES EMI GROUNDING PAD (MUST BE CONNECTED TO CHASSIS GROUND)



DETAIL G SCALE 2:1



DETAIL F

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PCB LAYOUT FOR BELLY TO BELLY CONFIGURATION
TOLERANCE: ±0.05
MINIMUM PCB THICKNESS OF 2.2 MM



TITLE: QSFP-DD 1X2 Cage Assembly w/ Heat Sink			
DWG#: H-OR-QD2-4CMFA3-TK		SHEET: 4/4	REV. REF.
UNIT: mm	SCALE: A4 2:1	CHECKED:	
THIRD ANGLE PROJECTION		APPROVED:	
TOLERANCE: Angle: ±1° X ± 0.15 .X ± 0.10 .XX ± 0.05		MATERIAL: RoHS, HF Compliant	DATE: 12/22/2020
		DRAWN: Jason Zhao	